Specification of Thermoelectric Module

TEHC1-16104

Description

The 161 couples, 40 mm \times 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74 $^{\circ}$ C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	21.2	22.8	Voltage applied to the module at DT _{max}	
I _{max(} amps)	4.8	4.8	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	64.9 70.9		Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	3.3	3.55	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

Positive lead wire (Red) 20AWG leads, PVC insulated Negative lead wire (Black) 150±3 Cold side:Tc See ordering option See ordering option

Manufacturing Options

A. Solder:	B. Sealant:

1. T100: BiSn (Tmelt=138°C) 1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C) 2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240°C) 3. EPS: Epoxy sealant

C. Ceramics: D. Ceramics Surface Options:

1. Alumina (Al₂O₃, white 96%) 1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN) 2. Metalized

Ordering Option

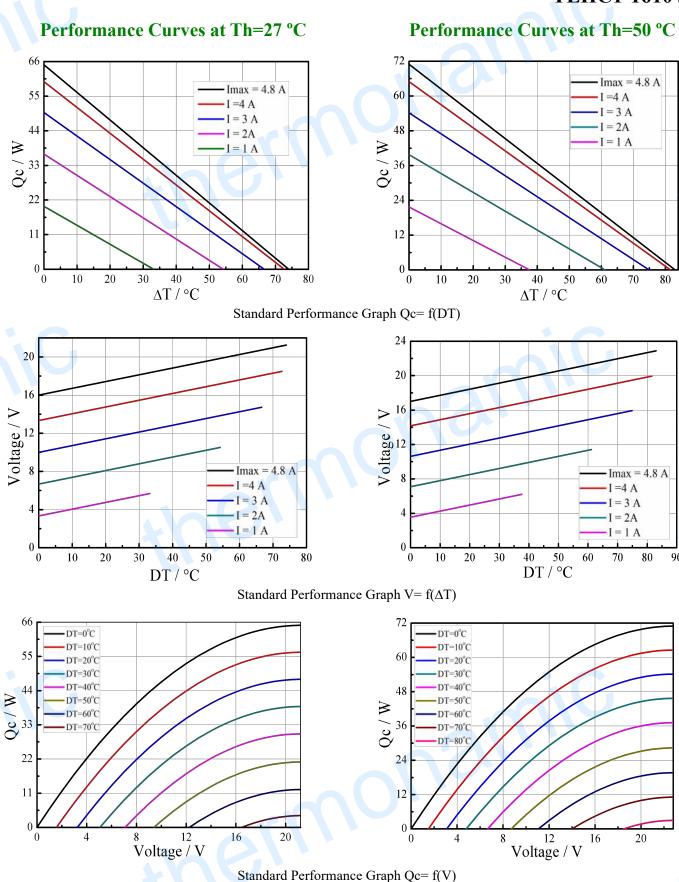
Naming for the Module

C. fe.	Thickness	Flatness/	Lead wire length(mm)			
Suffix	(mm)	Parallelism (mm)	Standard/Optional length			
TF	0:3.95±0.1	0:0.08/0.08	150±3/Specify			
TF	1:3.95±0.03	1:0.03/0.03	150±3/Specify			
Eg. TF01: Thickness 3.95±0.1(mm) and Flatness 0.03/0.03(mm)						

TEHC1-16104- X -X - X	- X
	Ceramics ——Flatness/ Parallelism
	Sealant Solder
TEHC1-16104-T100-N	S-TF01 -AlO
T100: BiSn(Tmelt=138°C)	
NS: No sealing	AlO: Alumina white 96%

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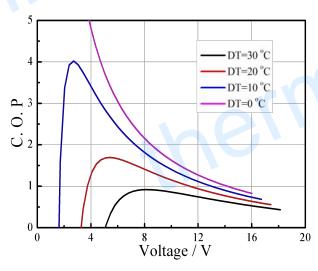


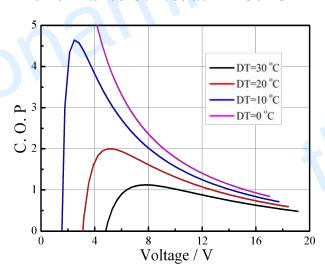
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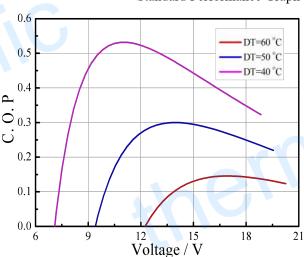
Performance Curves at Th=27 °C

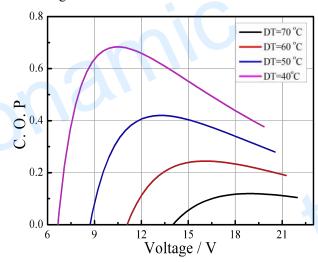
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC